

CHENBRO

Need An Extra Hand out There?

RB237 Series

2U High-Performance Server with Flexibility for Expansion

Featured with the dual 2nd Generation Intel® Xeon® Scalable processors and 24 DIMMs, RB237 Series delivers large memory capacity and high efficiency with various modularized storage and patented toolless design for HPC solutions.



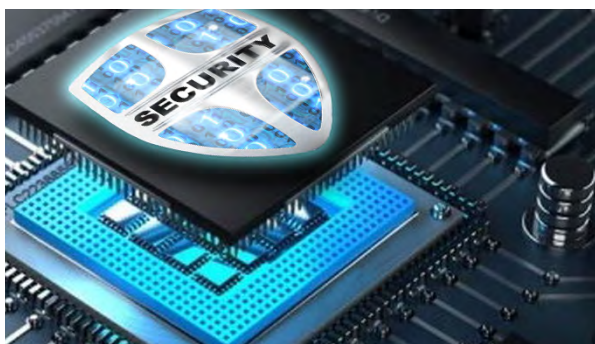
Powerful Compute with Flexible Expansion

RB237 Series is equipped with the dual 2nd Generation Intel® Xeon® Scalable processors, flexible expansion including RAID module and one OCP, and fulfills up to 7.5TB DDR4 ECC DIMM 2933 MT/s memory capacity to meet the critical requirements of IT, appliance, data center, cloud, and HPC applications.



Modularized Storage and Toolless Design

As a pioneer of rackmount chassis architects, we aim to provide reliable and modularized rackmount server for your best cost efficiency. RB237 Series offers hot-swap 2.5" or 3.5" SAS/SATA HDD trays, toolless fan module, hot-swap fans, and slide rails to optimize your OPEX and IT maintenance.



Leverage with Intel® VROC for Your Data Security

RB237 Series leverages Intel® VROC CPU to adopt PCIe slots to connect SSDs/HDDs directly for RAID construction without HBA and performs data protection solutions.

System Specifications

CPU	• Dual 2 nd Generation Intel® Xeon® Scalable processors, up to 165W
MB	• Intel S2600WFTR (Wolf Pass)
Memory	• 24 x DDR4 DIMM slot, 6 x channel per processor • Up to 7.5TB, DDR4 UDIMM ECC, 2933 MT/s, 1.2V
Dimension (D x W x H)	• 735.0 x 438.0 x 87.0 (mm) • 28.94" x 17.24" x 3.43"
Drive Bay	• RB23708-U1: 8 x 3.5" HDD, hot-swap (2 x 2.5" internal HDD/SSD, 1 x slim ODD) • RB23708-U2: 8 x 2.5" HDD/SSD, hot-swap • RB23712: 12 x 3.5" HDD, hot-swap
Cooling Fan	• 60 x 38 mm (6), hot-swap, 17K RPM
Power	• 800W CRPS, 80+ Platinum (single unit default)
Indicators	• 1 x Power Status, 2 x LAN Activity, 1 x UID
Front I/O	• 1 x Power Status, 2 x LAN Activity, 1 x UID, 1 x System Alarm • 1 x USB2.0 + 1 x USB3.0
Rear I/O	• 1 x UID • 2 x 10GbE Base-T, RJ-45, 1 x MGNT • 3 x USB3.0
Expansion Slot	• 4 x FHFL + 2 x FHHL + 2 x HHHL • 1 x I/O Module • 1 x Integrated RAID Module
Security	• TPM 2.0 support

Features & Benefits



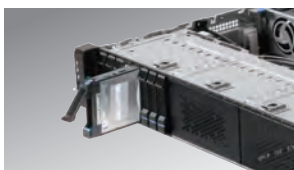
4 x PCIe Gen3 (FHFL), 2 x PCIe Gen3 (FHHL), 2 x PCIe Gen3 (HHHL)



Rear View



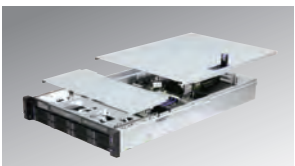
Hot-swap 8 x 3.5" HDD/12 x 3.5" HDD



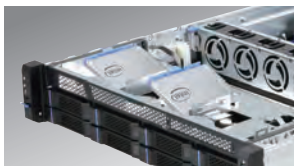
Hot-swap 8 x 2.5" HDD/SSD



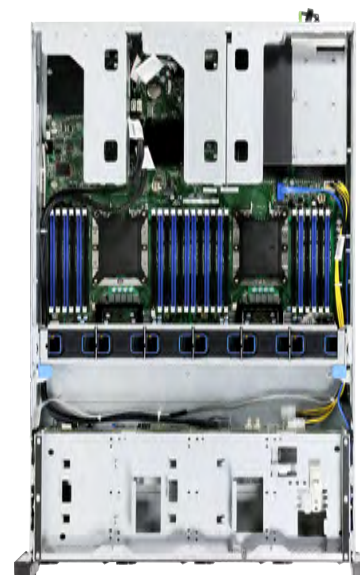
Hot-swap 60 x 38 mm cooling fans (6)



Toolless top cover and internal 2 x 2.5" HDD/SSD



Rack handle



RB23708-U1 Top View



RB23708-U2 Front View



RB23712 Front View



RB23708-U1 Front View

Chenbro

Founded in 1983, Chenbro (TWSE: 8210) has been the trailblazer in designing and manufacturing of own-brand rackmount system, tower server and PC chassis for over 37 years. Chenbro is not only qualified by the first-tier server brands and provides OEM, ODM and JDM services with EMS companies, but also successfully extends its business footprint to datacenters and industrial solutions by continuously investing in technology, and delivers the most trusted server and PC chassis with the highest standard of innovation. For more information about Chenbro, please visit www.chenbro.com.

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